

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1763mpde-1.8#trpbf

(Engineering Calculation)

DFN 4mm X 3mm Exp. Pad

(printed on: 2020-07-11 20:16:07)

**TOTAL MASS (g) : 0.031672**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001864	1000000	58853.546875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.012783	975000	403607.78125		
		Iron (Fe)	7439-89-6	0.000315	24000	9945.74511719		
		Phosphorus (P)	7723-14-0	0.000004	300	126.295173645		
		Zinc (Zn)	7440-66-6	0.000009	700	284.164154053		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.013111</b>	<b>1000000</b>	<b>413963.96875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000607	1000000	19160.0722656		
		<b>External Plating Total:</b>				<b>0.000607</b>	<b>1000000</b>	<b>19160.0722656</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000295	1000000	9314.26855469		
<b>Internal Plating Total:</b>				<b>0.000295</b>	<b>1000000</b>	<b>9314.26855469</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000876	750000	27658.640625		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000292	250000	9219.54785156		
<b>Die Attach Total:</b>				<b>0.001168</b>	<b>1000000</b>	<b>36878.1914062</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001888	130000	59611.3203125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.012487	860000	394261.9375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000145	10000	4578.19970703		
		<b>Encapsulation Total:</b>				<b>0.014520</b>	<b>1000000</b>	<b>458451.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000107	1000000	3378.39575195		
					<b>TOTAL MASS (g) :</b>	<b>0.031672</b>		